

1.6x0.8x0.5mm BI-COLOR SURFACE MOUNT **LED**

Part Number: APHB1608CGKSURKC

Green Hyper Red

Features

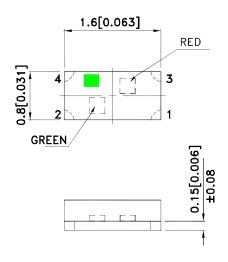
- 1.6mmX0.8mm SMT LED, 0.5mm thickness.
- Compatible with reflow soldering.
- Available in various color combination.
- Package: 2000pcs / reel .
- Moisture sensitivity level : level 3.
- Tinned pads for improved solderability.
- RoHS compliant.

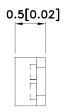
Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

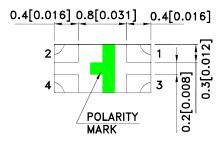
The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

Package Dimensions

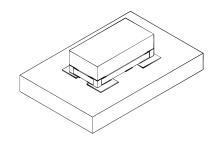








REV NO: V.2



SPEC NO: DSAK6423

APPROVED: WYNEC

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.15(0.006") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice. 4. The device has a single mounting surface. The device must be mounted according to the specifications.

CHECKED: Allen Liu

DATE: APR/19/2011 PAGE: 1 OF 6 DRAWN: J.Yu ERP: 1203011105

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,,	Min.	Тур.	201/2
APHB1608CGKSURKC	Green (AlGaInP)	Water Clear	12	40	130°
	Hyper Red (AlGaInP)	vvalei Ciedi	120	250	

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Green Hyper Red	574 650		nm	I==20mA	
λD [1]	Dominant Wavelength	Green Hyper Red	570 630		nm	I==20mA	
Δλ1/2	Spectral Line Half-width	Green Hyper Red	20 28		nm IF=20mA		
С	Capacitance	Green Hyper Red	15 35		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Green Hyper Red	2.1 1.95	2.5 2.5	V	I==20mA	
lR	Reverse Current	Green Hyper Red		10 10	uA	V _R = 5V	

Notes:

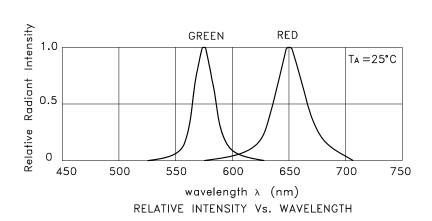
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

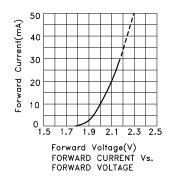
Parameter	Green	Hyper Red	Units		
Power dissipation	75	75	mW		
DC Forward Current	30	30	mA		
Peak Forward Current [1]	150	185	mA		
Reverse Voltage	5				
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

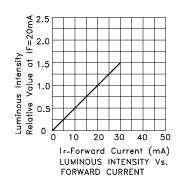
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

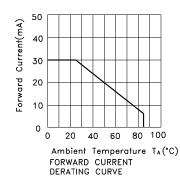
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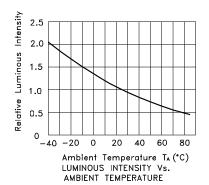


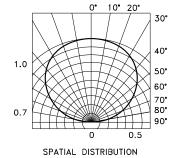
APHB1608CGKSURKC Green







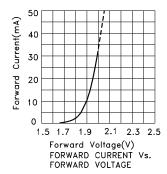


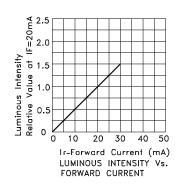


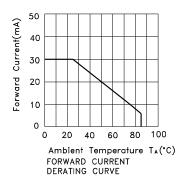
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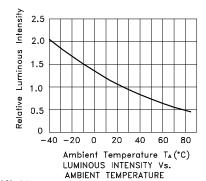
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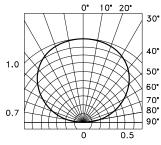
Hyper Red











SPATIAL DISTRIBUTION

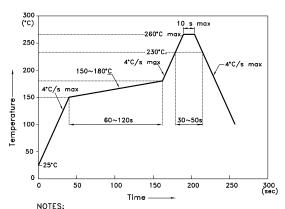
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



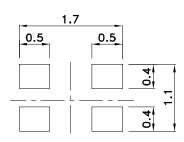
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

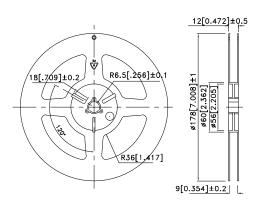
 3.Number of reflow process shall be 2 times or less.

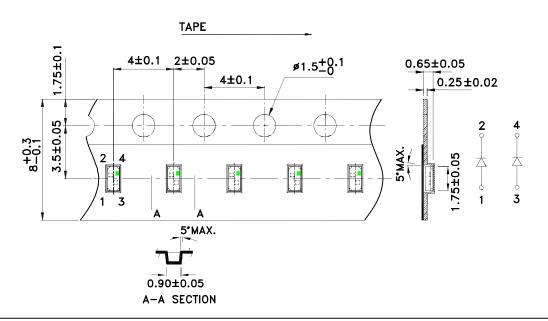
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units: mm)

Reel Dimension





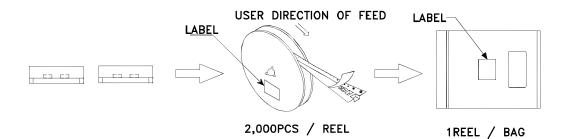
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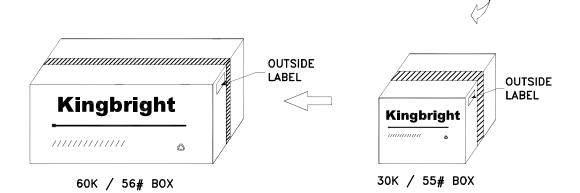
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PACKING & LABEL SPECIFICATIONS

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